

# Total solution for Flux cleaning

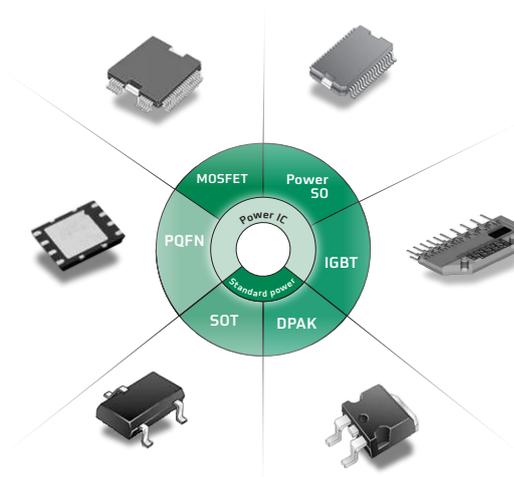
Leadframe Flux Cleaning after solder Die attach  
or Clip bonding with the new Mecox FXL

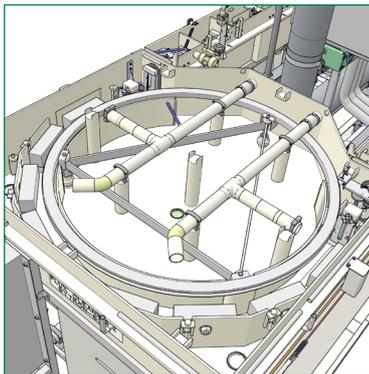
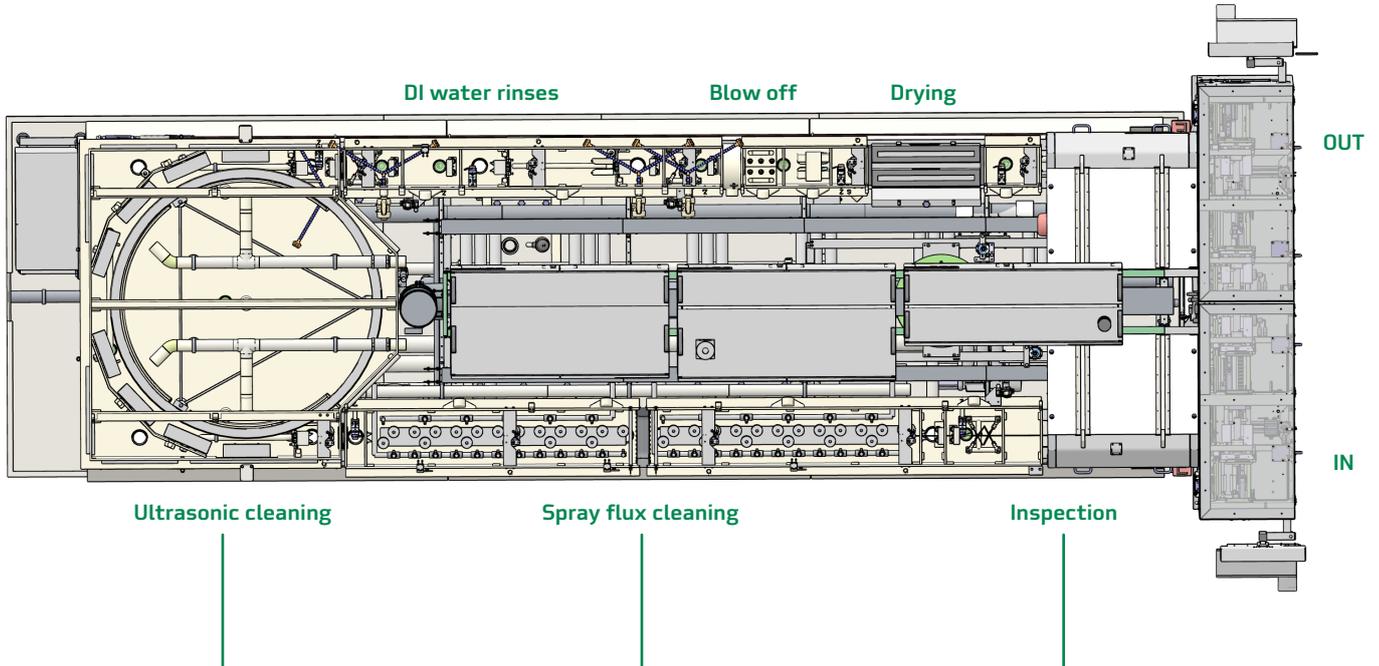
Besi and Sytron introduce the most advanced solution for lead frame flux cleaning with the new Mecox FXL and Water-Based Sytron Flux Cleaner. This newly innovated flux cleaner process effectively removes flux residue and other contaminants that arise during the die-attach process of semiconductor (lead frame) packages.

Clean devices ensure higher reliability (no delamination), improved wire-bonding and higher yield.

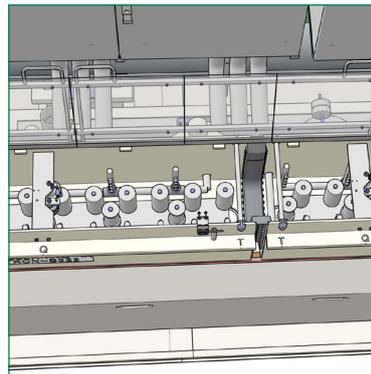
- Total solution, equipment with process from chemical Partner Sytron.
- Proven best in class cleaning process with water-based chemical (non-solvent, non-toxic, non-corrosive).
- Fully automated, high throughput tool with cassette-handling system and full product tracking (with 2D camera).
- Clean room compliant machine (FM4910 compliant materials) option.
- SECS GEM.
- Spray rinse, ultrasonic cleaning, or the unique combination of both.
- Guaranteed process capabilities: zero delamination, excellent wire bond reliability

## Future Proof Equipment

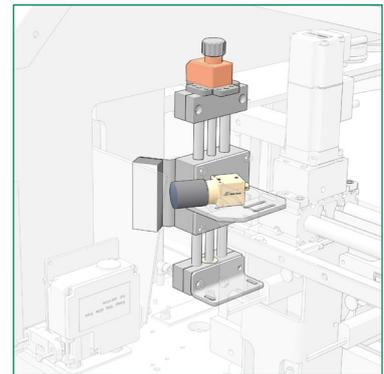




Easy access and optimal visibility of the defluxing process.



The vertical product transportation allows double side spray cleaning.



Full product tracing and data logging by means of 2D code reader.

### Meco FXL system

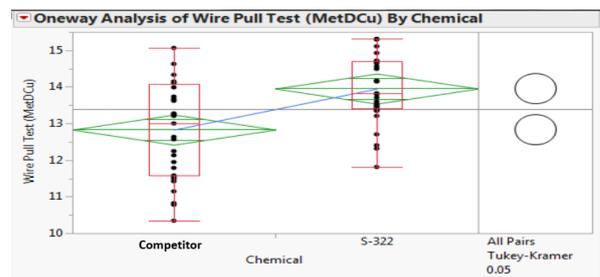
- Spray rinse in combination with ultrasonic cleaning.
- Excellent Process quality, Yield and Uniformity (All products receive exact same cleaning conditions)
- Low water, chemical and power consumption.
- Best Cost of Ownership.



Better wire-bonding (better ball shear and wire pull).

### Sytron FXL process

- Water-Based, non-toxic, non-solvent, non-corrosive chemical.
- No flashpoint, explosion proof protection
- Effective Flux Cleaning even at Room Temperature



Higher reliability - No delamination